
SPECIAL “MICROELECTRONICS” LABELS

1.0 SCOPE

This standard establishes special labeling requirements to be applied to packages, wraps, etc., containing MSD microelectronics parts, components, or assemblies.

2.0 REFERENCES

- 2.1 Lockheed Packaging Standard LPS 40-001 “General Requirement Specification”
- 2.2 Lockheed Product Protection Standard PPS-H325 “Microelectronics Parts and Assemblies (MSD use only)”
- 2.3 OD 14309 “Protection for FBM Material During Fabrication, Assembly, and Storage”

3.0 REQUIREMENTS

3.1 GENERAL

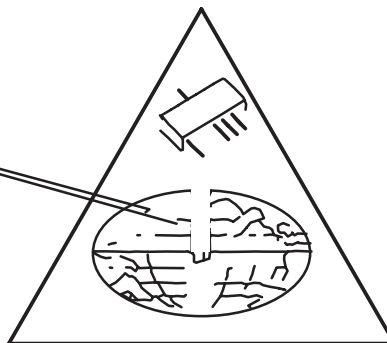
- 3.1.1 The microelectronics label requirements specified herein are in addition to any other container marking requirements imposed by the Procurement Document/Lockheed Packaging Standard (LPS).
- 3.1.2 The labels shall not cover other specified markings and shall not block inspection visibility on transparent packages.

3.2 MARKING – UNIT PACKAGES

Not Applicable

3.3 MARKING – INTERMEDIATE PACKAGES

- 3.3.1 Labels (See Figure 1) shall be affixed to each intermediate package.
- 3.3.2 When large size containers are included, apply additional microelectronics labels to opposite sides/ends of container to assure visibility.
- 3.3.3 Select and apply an appropriate size label(s) commensurate with the size of the container(s).



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